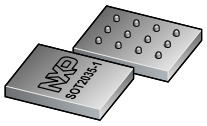

SOT2035-1

WLCSP12, wafer level chip scale package, 12 terminals, 0.25 mm pitch, 1.185 mm x 0.935 mm x 0.22 mm body

27 January 2020 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP12
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	24-10-2019
Manufacturer package code	98ASA01491D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.905	0.935	0.965	mm
package width	1.155	1.185	1.215	mm
package height	-	0.22	0.24	mm
nominal pitch	-	0.25	-	mm
actual quantity of termination	-	12	-	

WLCSP12, wafer level chip scale package, 12 terminals, 0.25 mm pitch, 1.185 mm x 0.935 mm x 0.22 mm body

2 Package outline

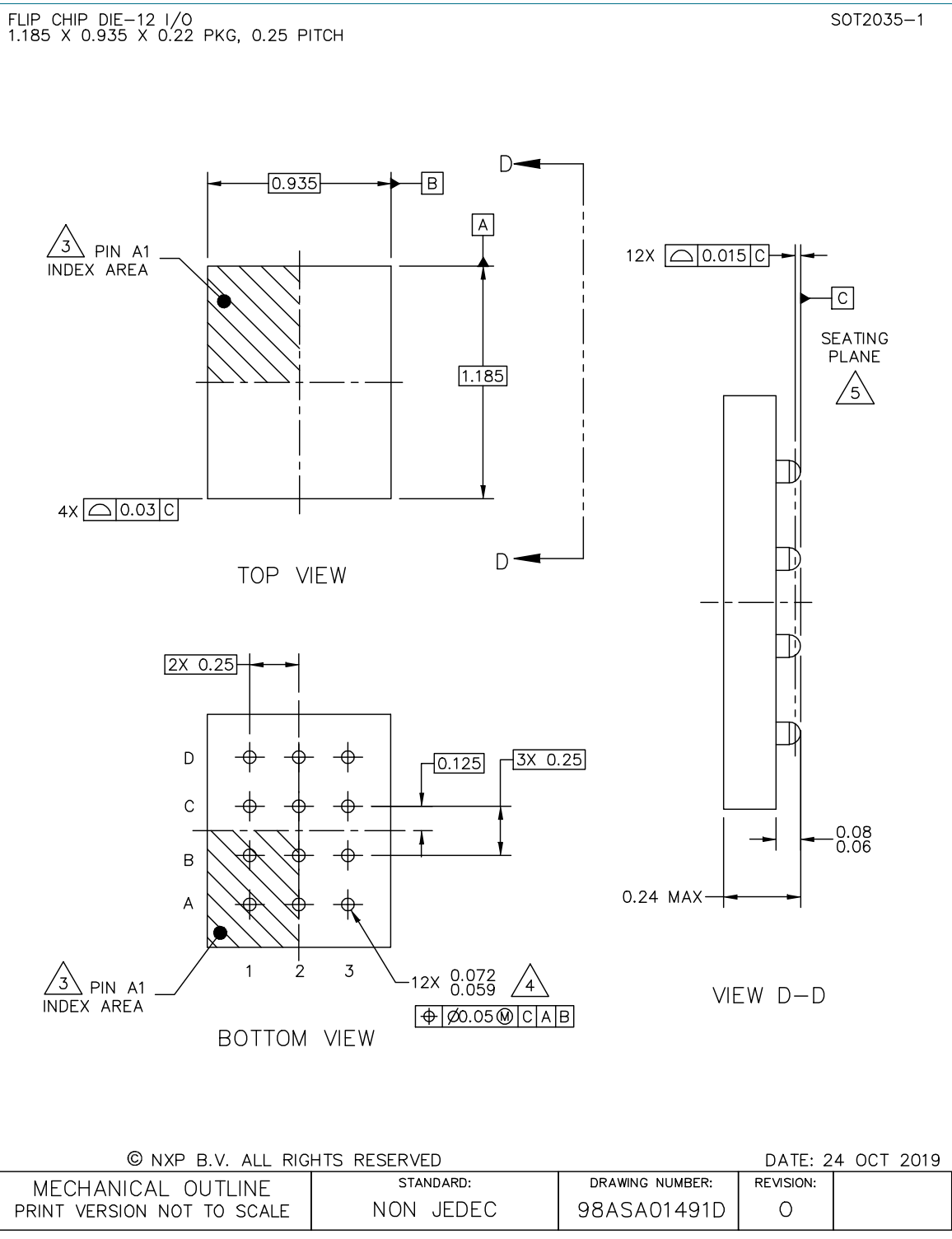

Figure 1. Package outline WLCSP12 (SOT2035-1)

WLCSP12, wafer level chip scale package, 12 terminals, 0.25 mm pitch, 1.185 mm x 0.935 mm x 0.22 mm body

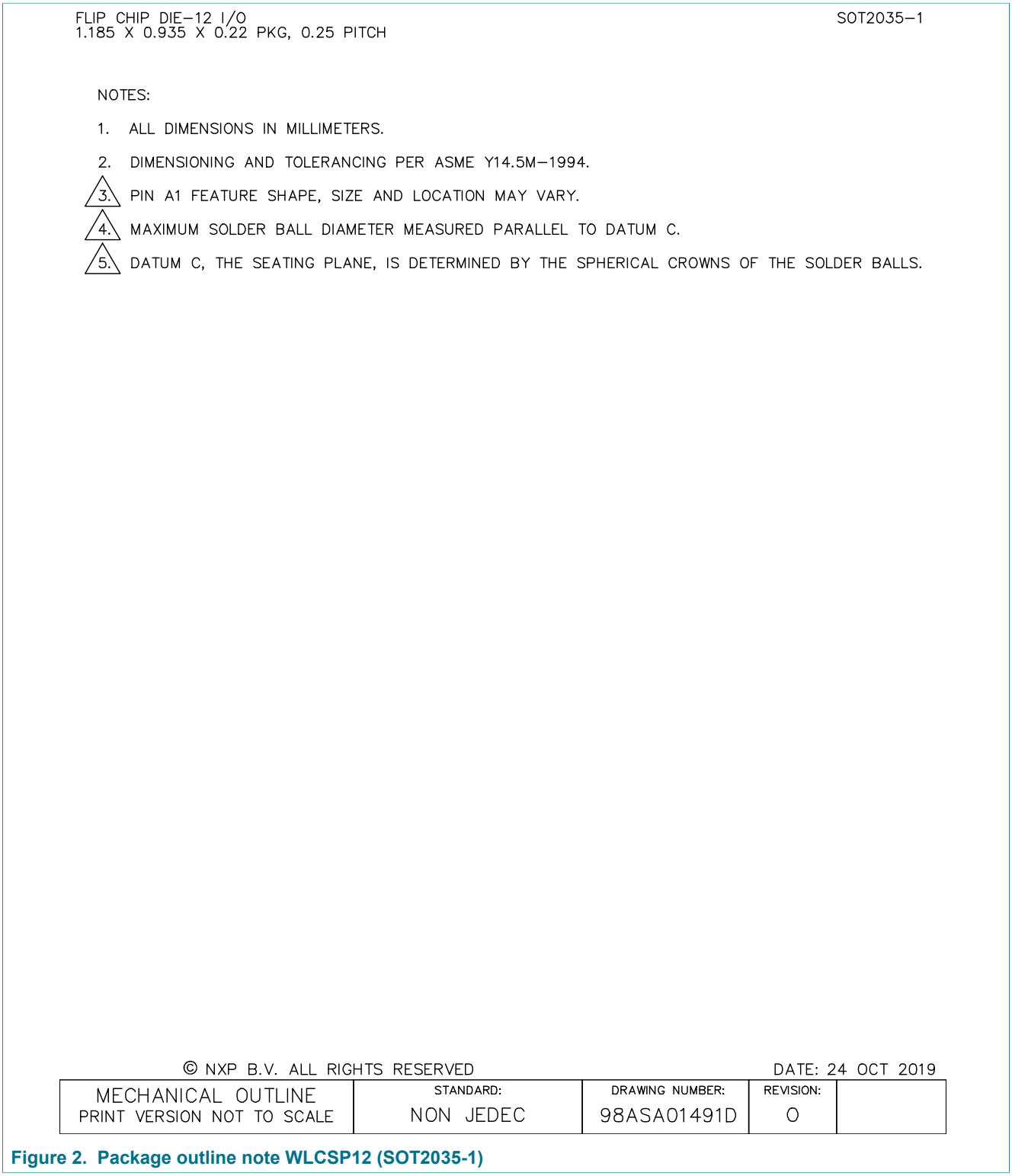

Figure 2. Package outline note WLCSP12 (SOT2035-1)

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SOT2035-1

WLCSP12, wafer level chip scale package, 12 terminals, 0.25 mm pitch, 1.185 mm x 0.935 mm x 0.22 mm body

Contents

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